



ES3ABG THRU ES3JBG

Reverse Voltage - 50 to 600 Volts Forward Current - 3.0 Ampere

SURFACE MOUNT SUPER FAST RECOVERY RECTIFIER

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
 - ◆ 250°C/10 seconds at terminals
 - ◆ Glass passivated chip junction

Mechanical Data

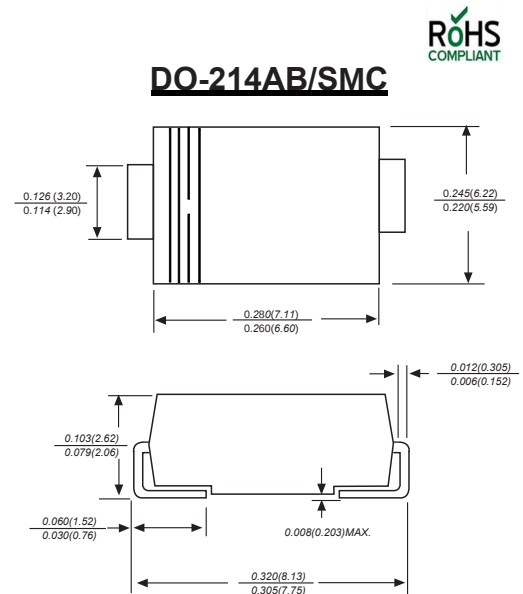
Case : JEDEC DO-214AB/SMC Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.002 ounce, 0.055 grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	ES3ACG	ES3BCG	ES3CCG	ES3DCG	ES3ECG	ES3GCG	ES3JCG	UNITS
Marking Code		MDD ES3AC	MDD ES3BC	MDD ES3CC	MDD ES3DC	MDD ES3EC	MDD ES3GC	MDD ES3JC	
Maximum repetitive peak reverse voltage	V _{RMM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V _{RMS}	35	70	105	140	210	280	420	V
Maximum DC blocking voltage	V _{DC}	50	100	150	200	300	400	600	V
Maximum average forward rectified current at TL=55℃	I _(AV)	3.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed onrated load (JEDEC Method)	I _{FSM}	90							A
Maximum instantaneous forward voltage at 3.0A	V _F	1				1.25		1.68	V
Maximum DC reverse current TA=25℃ at rated DCblocking voltage TA=125℃	I _R	5.0 100.0							μA
Maximum reverse recovery time (NOTE 1)	t _{rr}	35							ns
Typical junction capacitance (NOTE 2)	C _J	40.0							pF
Typical thermal resistance (NOTE 3)	R _{θJA}	40.0							℃/W
Operating junction and storage temperature range	T _J , T _{STG}	-55 to +150							℃

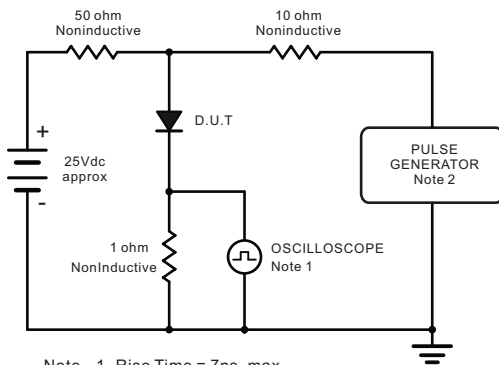
- Note:** 1. Reverse recovery condition $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{rr}=0.25\text{A}$
2. P.C.B. mounted with 1.0x1.0" (2.54x2.54cm) copper pad areas.
3. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
4. The typical data above is for reference only.



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Ratings And Characteristic Curves



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1megohm, 22pF.
2. Rise Time = 10ns, max.
Source Impedance = 50 ohms.

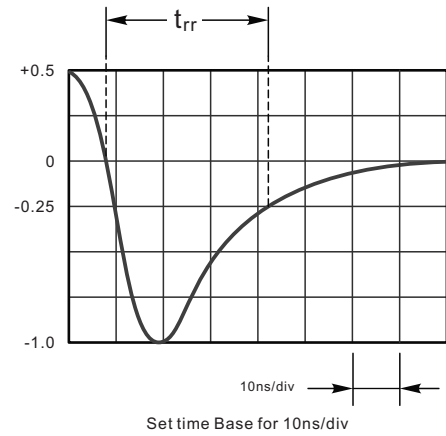


Fig.2 Maximum Average Forward Current Rating

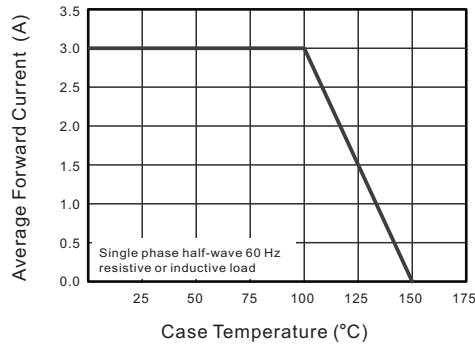


Fig.3 Typical Reverse Characteristics

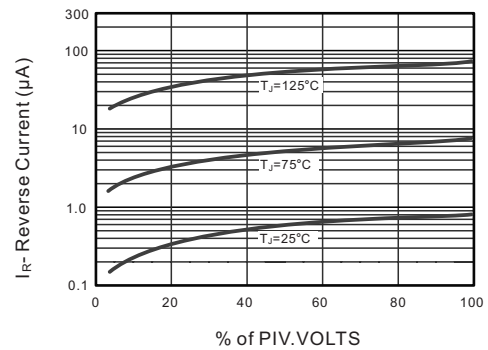


Fig.4 Typical Forward Characteristics

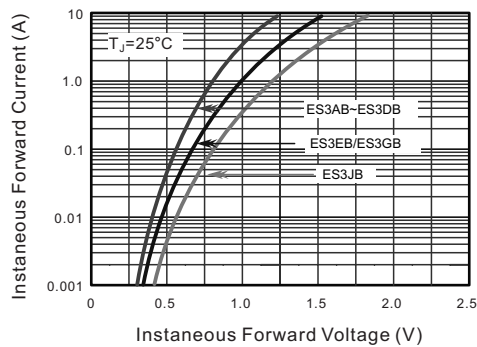


Fig.5 Typical Junction Capacitance

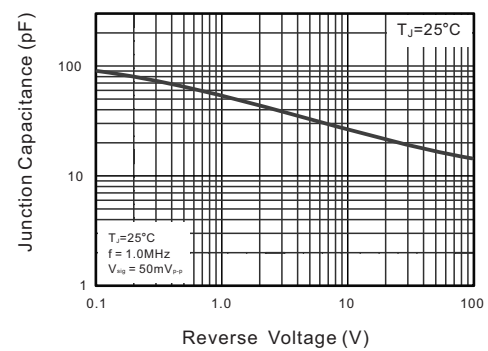
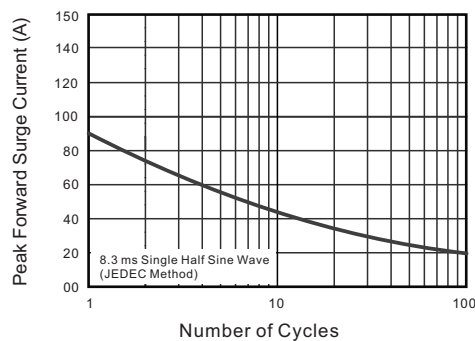


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current



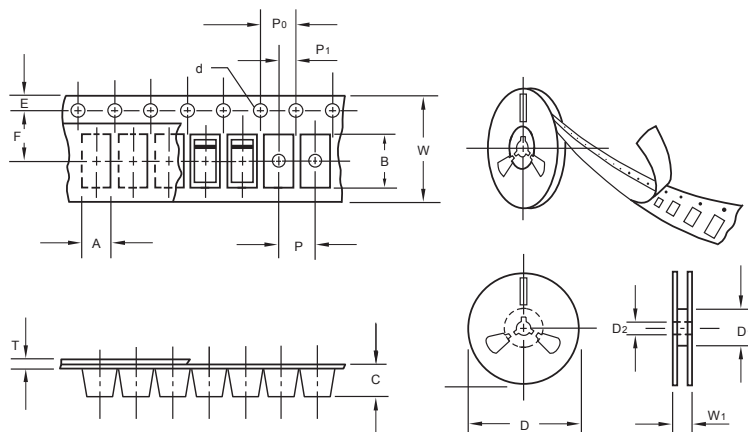
The curve above is for reference only.



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Packing information



unit:mm

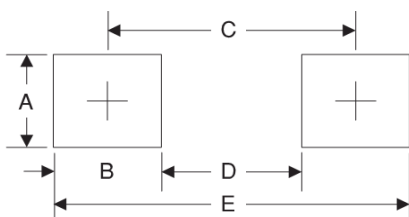
Item	Symbol	Tolerance	SMC
Carrier width	A	0.1	6.15
Carrier length	B	0.1	8.41
Carrier depth	C	0.1	2.42
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D1	min	50.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	7.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.25
Tape width	W	0.3	16.00
Reel width	W1	1.0	16.50

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA, (mm)	CARTON SIZE (mm)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMC	13"	3,000	4.0	6000	190*190*41	330	365*365*340	42000	14.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	4.3	0.170
B	4.1	0.160
C	7.9	0.311
D	3.8	0.150
E	12	0.472

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